

# Defect kinetics in Epi/Cz silicon after $\text{Co}^{60}$ - $\gamma$ irradiation

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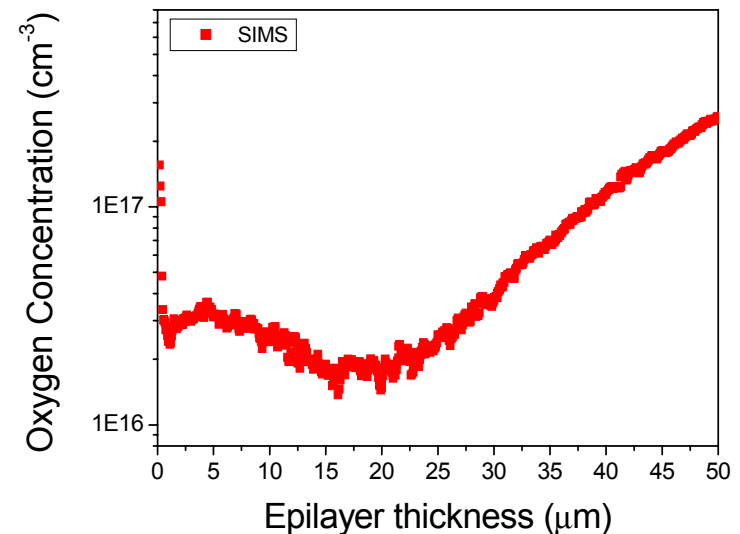
**Motivation-** The divacancy annealing mechanisms proposed for STFZ after low irradiation doses cannot explain the results obtained in Epi/Cz diodes after high doses of irradiation

EPI-Silicon wafers: <111>, n/P, 50 Ωcm, 50 μm on 300 μm Cz-substrate, CiS process

Irradiation source: Brookhaven National Laboratory for <sup>60</sup>Co-γ-photons

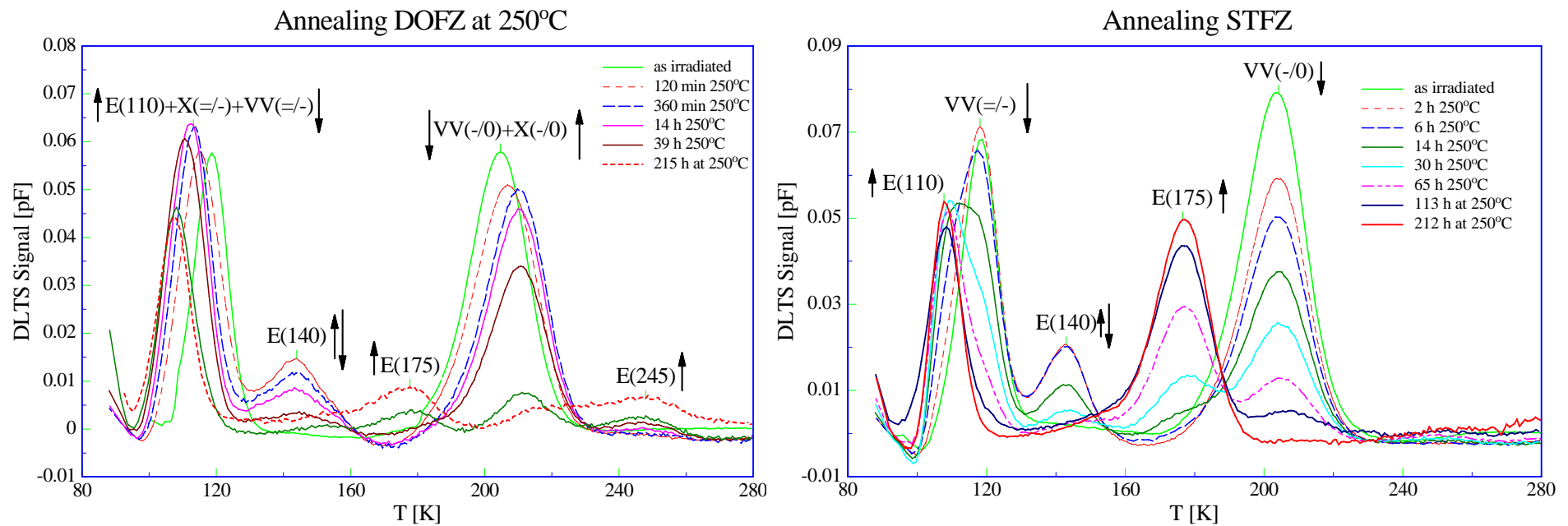
Sample	STFZ	DOFZ	EPI/Cz
SIMS [O]	<5*10 <sup>16</sup>	1.2*10 <sup>17</sup>	(1.5- 30)*10 <sup>16</sup>

Carbon concentration for all materials at detection limit [C] ≈ 5.7×10<sup>15</sup> cm<sup>-3</sup>



# Annealing experiments

- *low irradiation doses* (4 Mrad) – the X defect is formed in oxygen enriched material via the annealing of divacancy for  $T > 250^\circ\text{C}$



**X defect – two acceptor states - Identified as  $V_2O$  <sup>1)</sup>**

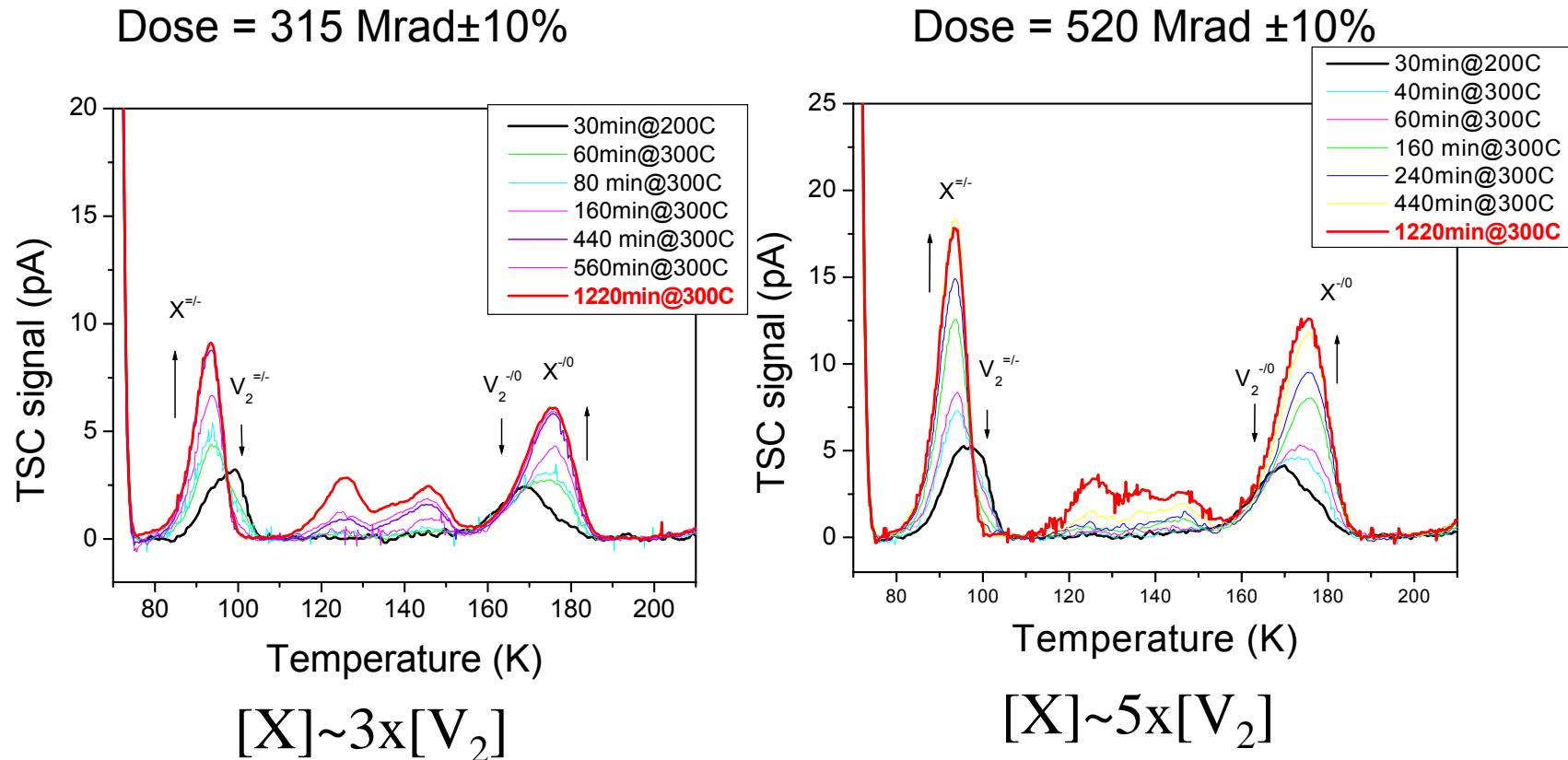
**Proposed formation mechanism<sup>1)</sup>:  $V_2 + O_i \Rightarrow V_2O$**

**(with  $D_{V_2} = 3 \times 10^{-3} \exp(-1.3\text{eV})$  instead of the former  $D_{V_2} = 0.1 \exp(-1.3\text{eV})$ )**

<sup>1)</sup> Monakov et al, Phys Rev B, Volume 65, 233207 (2002)

- *high irradiation doses* (>100 Mrad) – **X center formed in concentration higher than of  $V_2$  for  $T > 250^\circ\text{C}$**

**Epi/Cz material –  $T = 300^\circ\text{C}$**



**X defect – Identified as  $V_2O_2$  <sup>2)</sup> via:  $V_2 + O_2 \Rightarrow V_2O_2$  and  $VO + VO$**

(with  $D_{V_2} = 0.1 \exp(-1.3\text{eV})$  and  $D_{VO}(T) = 6 \exp(-1.8\text{eV}/KT) \text{ cm}^2/\text{s}$ )

<sup>2)</sup> I.Pintilie et al- 6<sup>th</sup> and 7<sup>th</sup> RD50 workshops

***Which defect reactions at  $T > 250$  C can produce more  $V_2O$  ?***

- $V_2 + O \rightarrow V_2O$
- $V + VO \rightarrow V_2O$

**$\Rightarrow$  Should exist a source of V**

• Most probable VO can be the V source – it dissociates during annealing at  $T > 250$  C



# Defect reactions

## Vacancy-Oxygen related defect reactions

### Diffusion reactions

- $V + O \rightarrow VO$
- $V + VO \rightarrow V_2O$
- $V + V \rightarrow V_2$
- $V_2 + O \rightarrow V_2O$
- $V_2 + O_2 \rightarrow V_2O_2$
- $V + O_2 \rightarrow VO_2$
- $VO + O \rightarrow VO_2$
- $V + VO_2 \rightarrow V_2O_2$
- $VO + VO \rightarrow V_2O_2$

### Dissociation reactions

- $VO \rightarrow V + O$
- $V_2O \rightarrow V + VO$
- $V_2O_2 \rightarrow VO + VO$
- $V_2 \rightarrow V + V$

## Defect reactions with other impurities\*

### Diffusion reactions

- $VO + H \rightarrow VOH$
- $V_2 + H \rightarrow V_2H$
- $V + H \rightarrow VH$
- $CiOi + H \rightarrow COH$
- $V + CiOi \rightarrow CsOi$
- $Ci + V \rightarrow Cs$
- $Ci + Oi \rightarrow CiOi$
- $V + CiCs \rightarrow CsCs$

### Dissociation reactions

- $VOH \rightarrow VO + H$
- $V_2H \rightarrow V + VH$
- $VH \rightarrow V + H$
- $CiCs \rightarrow Ci + Cs$

\*Do not affect the V-O defect reactions as long as  $[H] < 10^{15} \text{ cm}^{-3}$

# Parameters used for simulations

- $[O_i]$  = profile from SIMS
- $[VO] = 1.1 \times 10^{12} \times \text{Dose (Mrad)} \times \text{cm}^{-3}$
- $r = 5 \times 10^{-10} \text{m}$

## **Diffusion parameters**

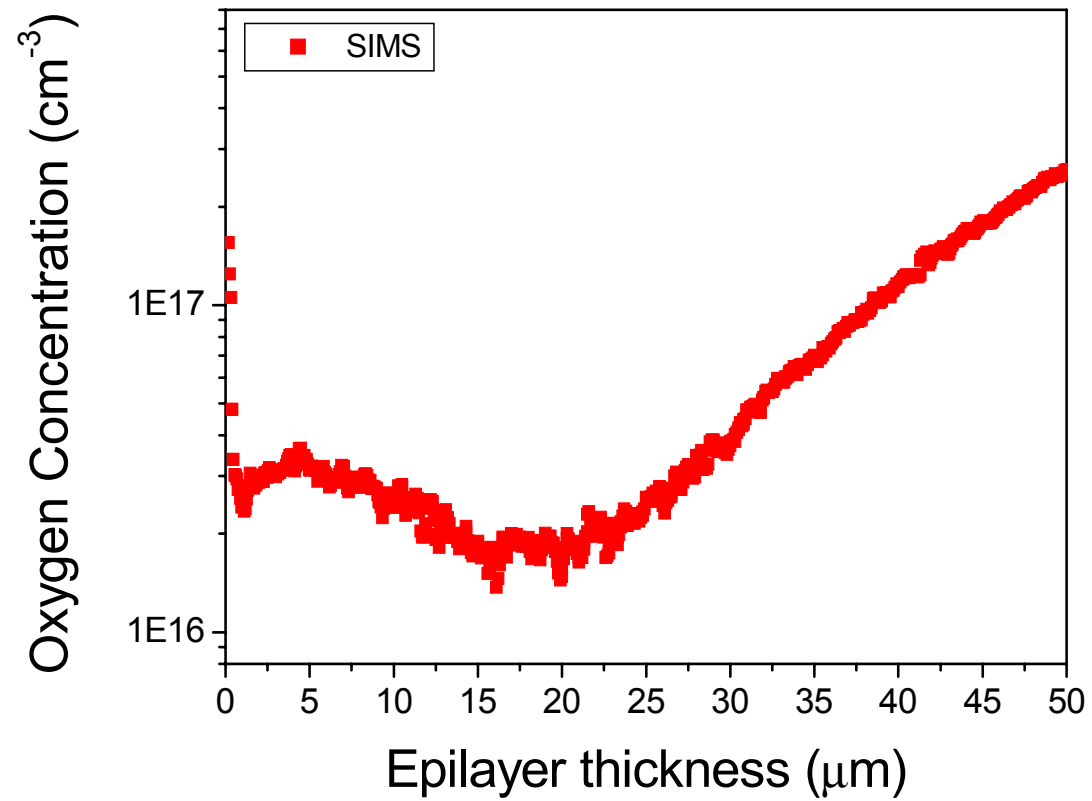
*(updated to nowadays literature)*

- $D_{VO}(T) = 6 \exp(-1.8 \text{eV}/KT) \text{ cm}^2/\text{s}$ ;
- $D_{VV}(T) = 3 \times 10^{-3} \exp(-1.3 \text{eV}/KT) \text{ cm}^2/\text{s}$ ;
- $D_{Od}(T) = 3 \times 10^{-4} \exp(-1.3 \text{eV}/KT) \text{ cm}^2/\text{s}$ ;
- $D_{oi}(T) = 0.17 \exp(-2.54 \text{eV}/KT) \text{ cm}^2/\text{s}$
- $D_V(T) = 4.5 \times 10^{-4} \exp(-0.3 \text{eV}/KT) \text{ cm}^2/\text{s}$ ;
- $D_{Ci}(T) = 4.4 \times 10^{-1} \exp(-0.87 \text{eV}/KT) \text{ cm}^2/\text{s}$ ;

## **Dissociation**

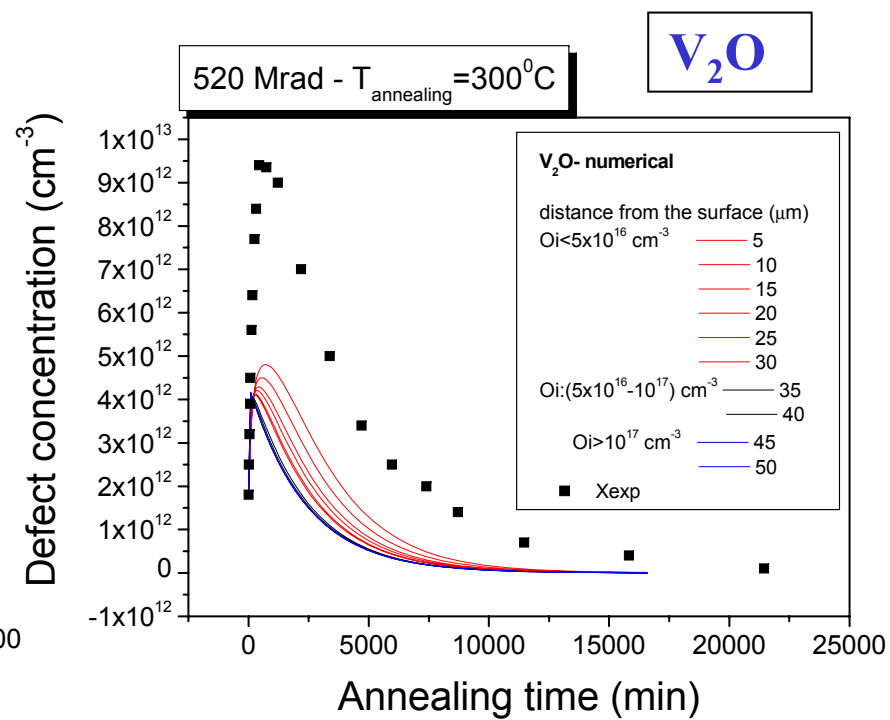
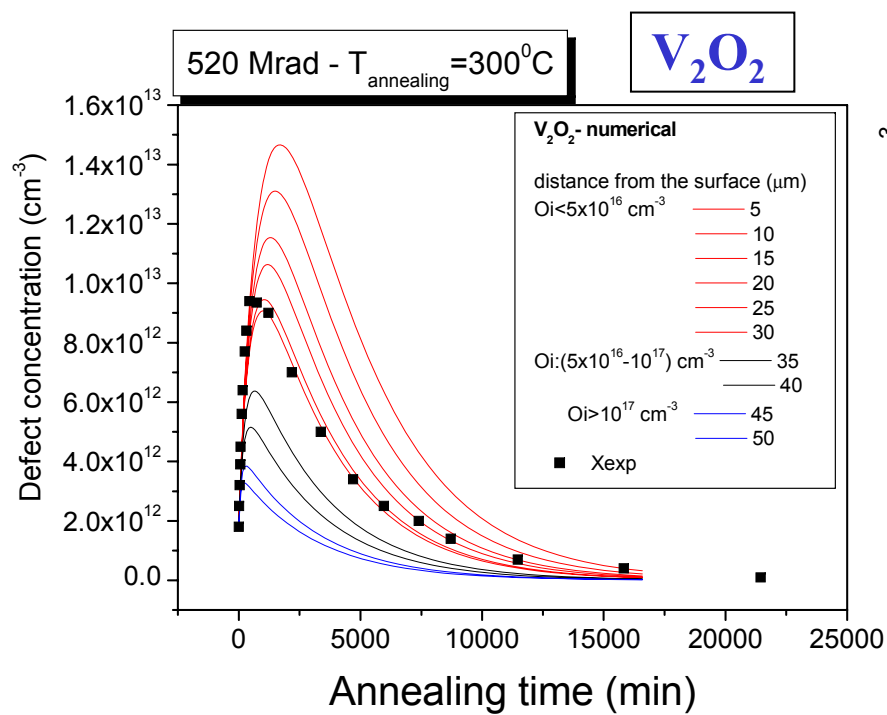
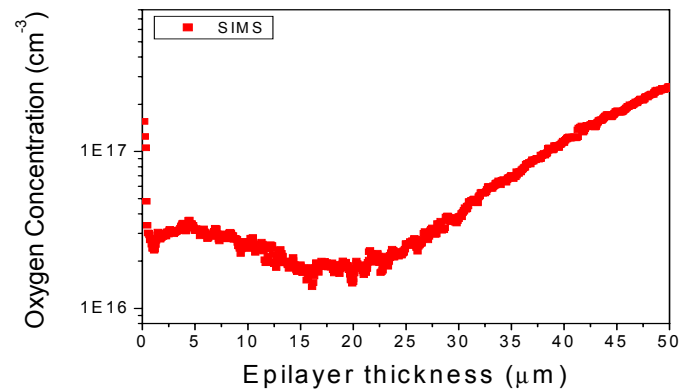
- $K^{VO} = 1 \times 10^{13} \exp(-2.1 \text{eV}/KT) \text{ s}^{-1}$ ;
- $K^{V2O2} = 1.5 \times 10^{13} \exp(-2.1 \text{eV}/KT) \text{ s}^{-1}$
- $K^{V2O} = 2 \times 10^{13} \exp(-2.1 \text{eV}/KT) \text{ s}^{-1}$

## *$O_i$ profile - from SIMS measurements*

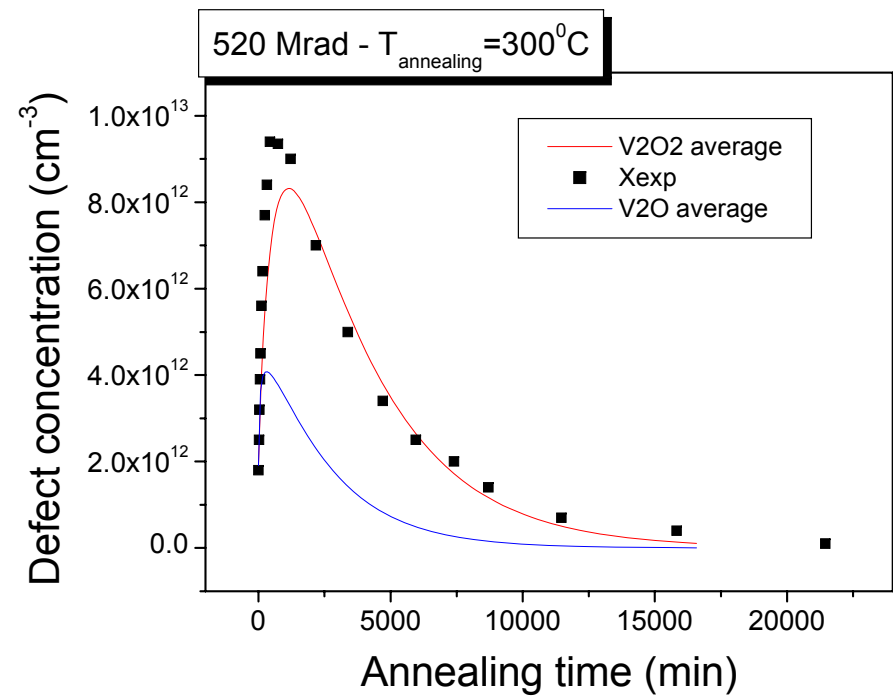
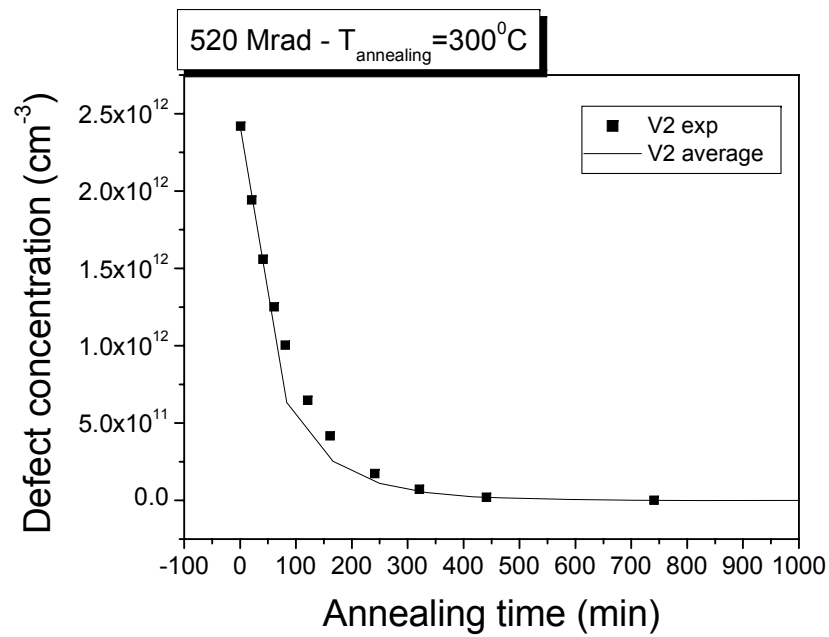




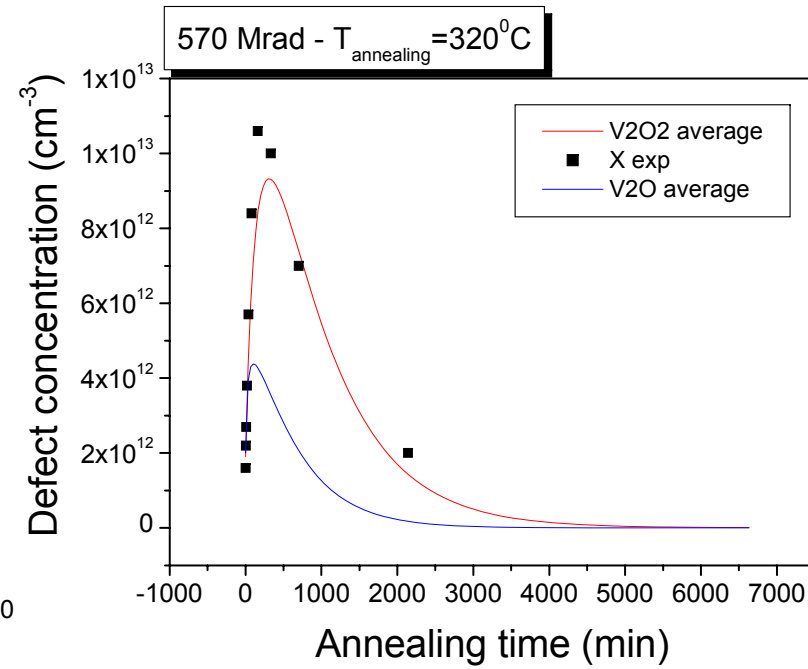
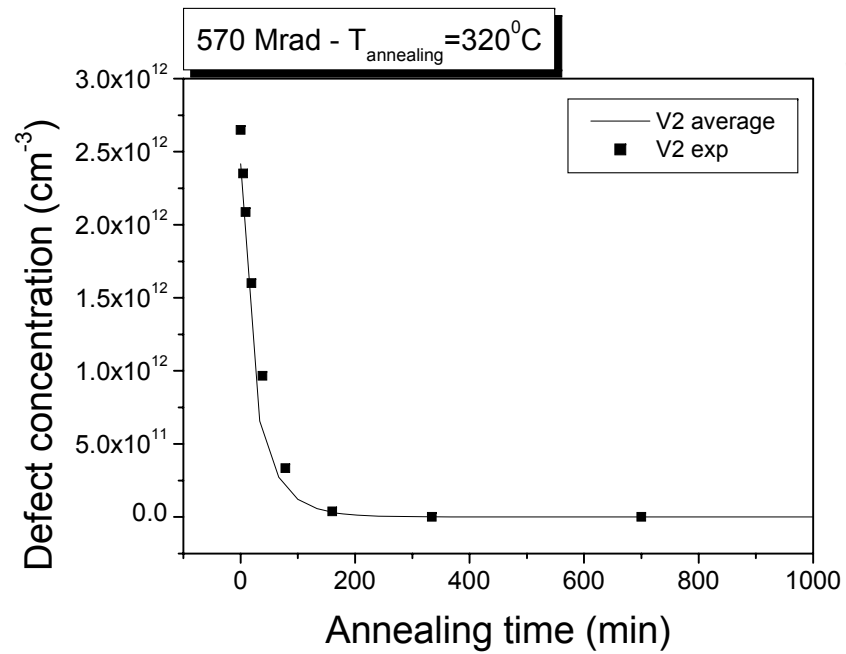
520 Mrad -  $T=300^{\circ}\text{C}$



# 520 Mrad - T=300°C



# 570 Mrad - T=320°C



# Conclusions

- Simulations based on a more complex system of defect reactions show that both  $V_2O$  and  $V_2O_2$  defects should form at elevated temperature.
- With VO as single initial source for vacancies and for the irradiation dose range investigated here:
  - ⇒  $V_2O_2$  can be produced in a similar concentration with X center
  - ⇒  $V_2O$  can be produced in a concentration higher than  $V_2$  but in a much smaller concentration than of the X center
- Further studies are under discussion regarding the existence of additional single V migrating from Cz substrate.